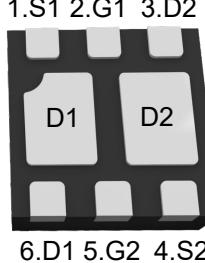
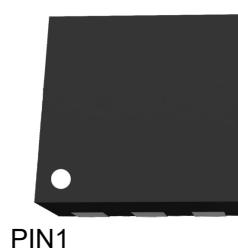


## Features

- Low gate charge and  $R_{DS(ON)}$
- $V_{DS} = -20V, I_D = -3A$
- $R_{DS(on)} < 55m\Omega$  @  $V_{GS} = -10V$

## Dual P-Channel Enhancement Mode Power MOSFET

### DFN2x2A-6L



PIN1

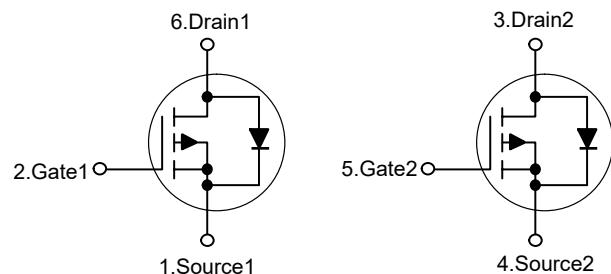
 1.S1 2.G1 3.D2  
6.D1 5.G2 4.S2

**Marking Code: 03DP20**

## Applications

- PWM applications
- Load Switch for Portable Devices
- Power management

## Schematic Diagram



## Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-20	V
Gate-Source Voltage			$V_{GSS}$	$\pm 8$	V
Continuous Drain Current (Note 5) $V_{GS} = -4.5V$	Steady State	$T_A = +25^\circ C$	$I_D$	-3.8	A
		$T_A = +70^\circ C$		-3.0	
Maximum Continuous Body Diode Forward Current (Note 5)			$I_S$	-1.0	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)			$I_{DM}$	-25	A
Avalanche Current (Note 7) $L = 0.1mH$			$I_{AS}$	-13	A
Avalanche Energy (Note 7) $L = 0.1mH$			$E_{AS}$	8.5	mJ

## Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^\circ C$	$P_D$	0.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	178	°C/W
Total Power Dissipation (Note 6)	$T_A = +25^\circ C$	$P_D$	1.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	92	°C/W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	22	
Operating and Storage Temperature Range	$T_J, T_{STG}$		-55 to +150	°C

**Electrical Characteristics**

(Ta=25°C unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 8)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	—	—	-1.0	μA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±10	μA	V <sub>GS</sub> = ±6.4V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 8)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.35	—	-1.4	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	53	75	mΩ	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2.9A
		—	64	137		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -2.3A
Diode Forward Voltage	V <sub>SD</sub>	—	-0.7	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -3.0A
<b>DYNAMIC CHARACTERISTICS (Note 9)</b>						
Input Capacitance	C <sub>iss</sub>	—	642	—	pF	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	98	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	87	—	pF	
Gate Resistance	R <sub>g</sub>	—	26.5	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Q <sub>g</sub>	—	8.8	—	nC	V <sub>DS</sub> = -10V, I <sub>D</sub> = -3.7A
Total Gate Charge (V <sub>GS</sub> = -8V)		—	15	—	nC	
Gate-Source Charge	Q <sub>gs</sub>	—	0.9	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	2.9	—	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	—	5.5	—	ns	
Turn-On Rise Time	t <sub>R</sub>	—	22.6	—	ns	V <sub>DD</sub> = -10V, V <sub>GS</sub> = -4.5V, R <sub>L</sub> = 3.3Ω, R <sub>g</sub> = 1Ω
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	34.1	—	ns	
Turn-Off Fall Time	t <sub>F</sub>	—	34.3	—	ns	
Body Diode Reverse Recovery Time	t <sub>RR</sub>	—	13	—	ns	I <sub>S</sub> = -3.0A, dI/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	—	3.3	—	nC	I <sub>S</sub> = -3.0A, dI/dt = 100A/μs

Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided

6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.

7. I<sub>S</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.

8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.

## Typical Characteristic Curves

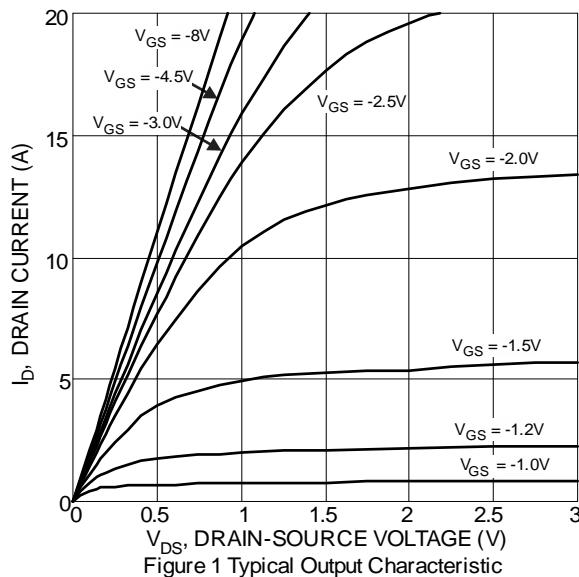


Figure 1 Typical Output Characteristic

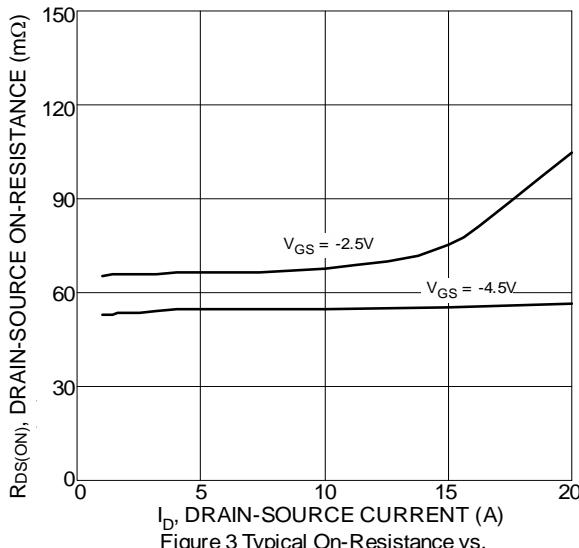
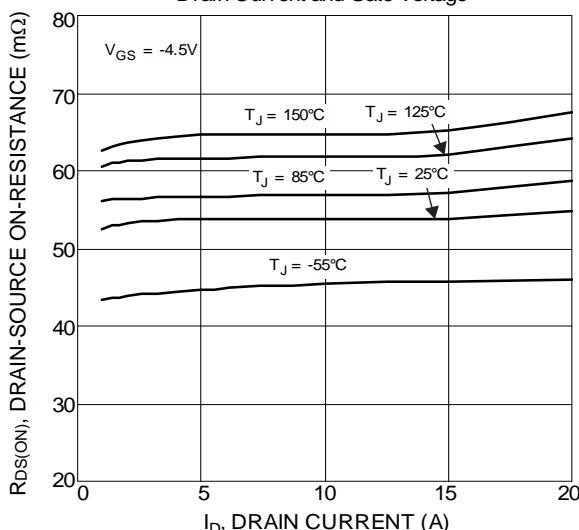
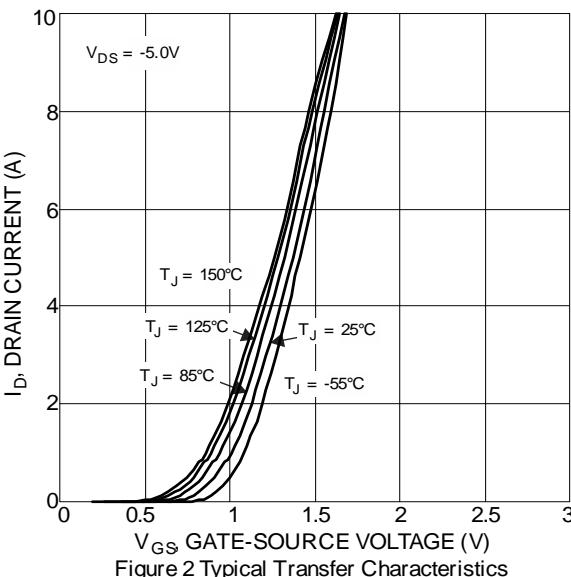
Figure 3 Typical On-Resistance vs.  
Drain Current and Gate VoltageFigure 5 Typical On-Resistance vs.  
Drain Current and Temperature

Figure 2 Typical Transfer Characteristics

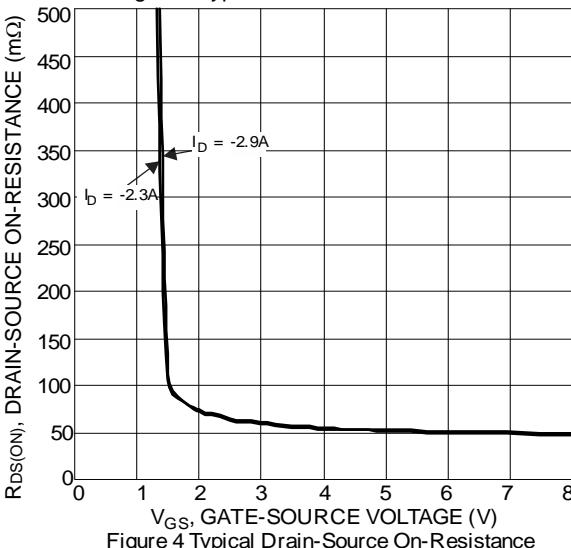
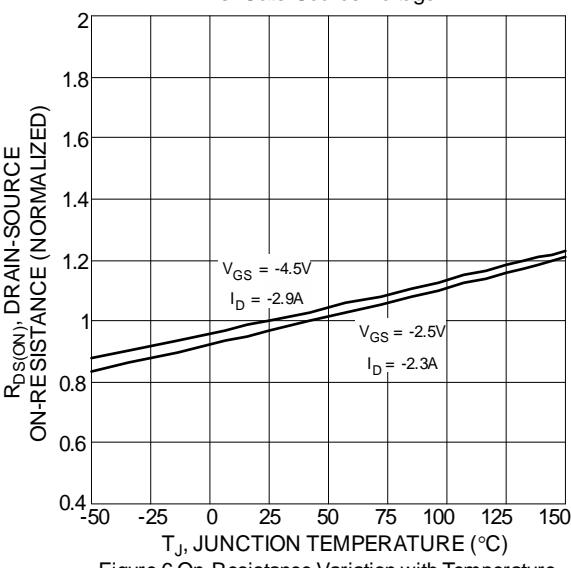
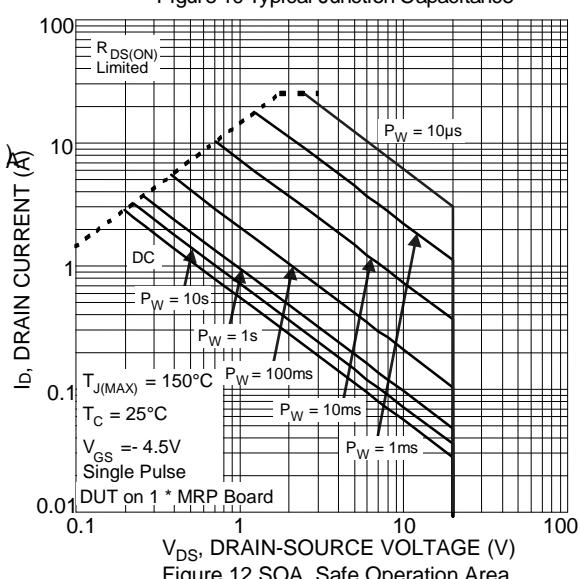
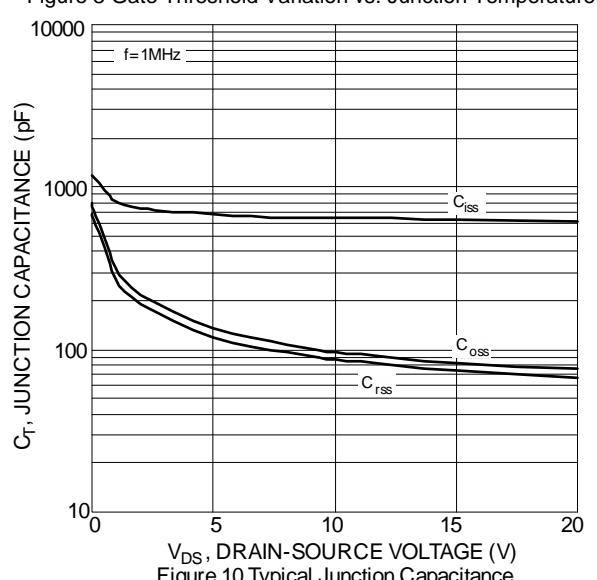
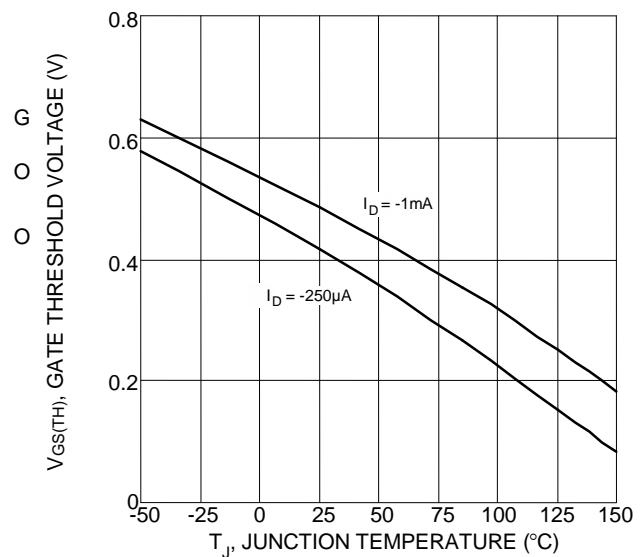
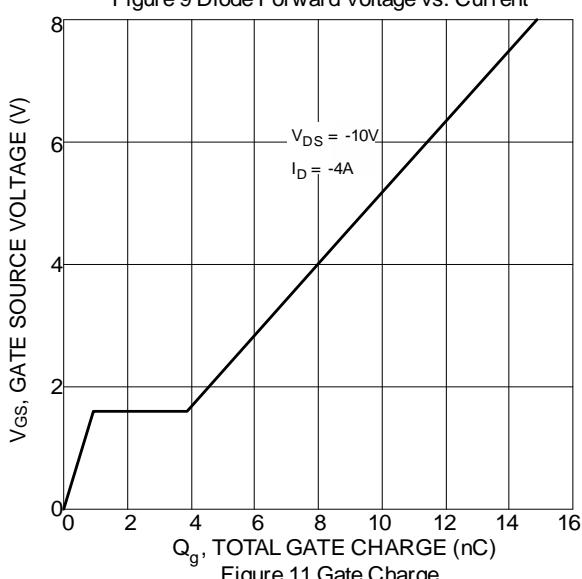
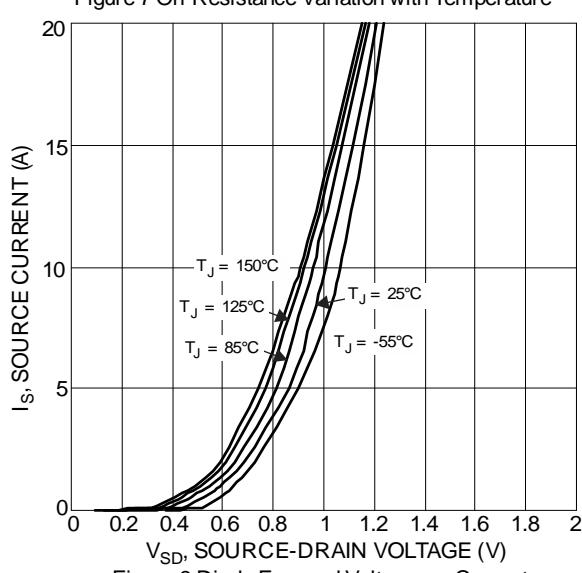
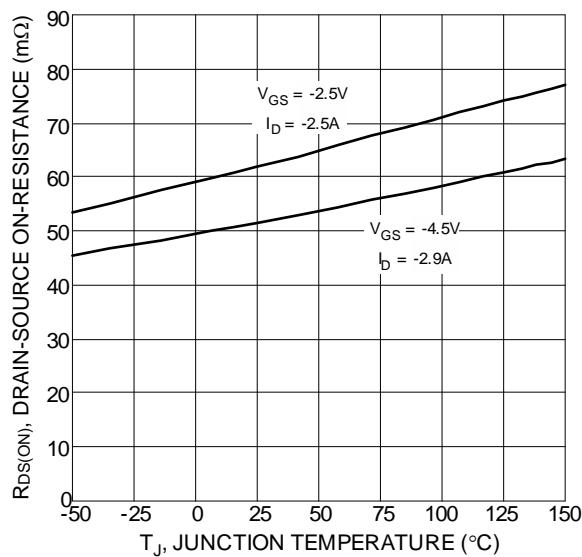
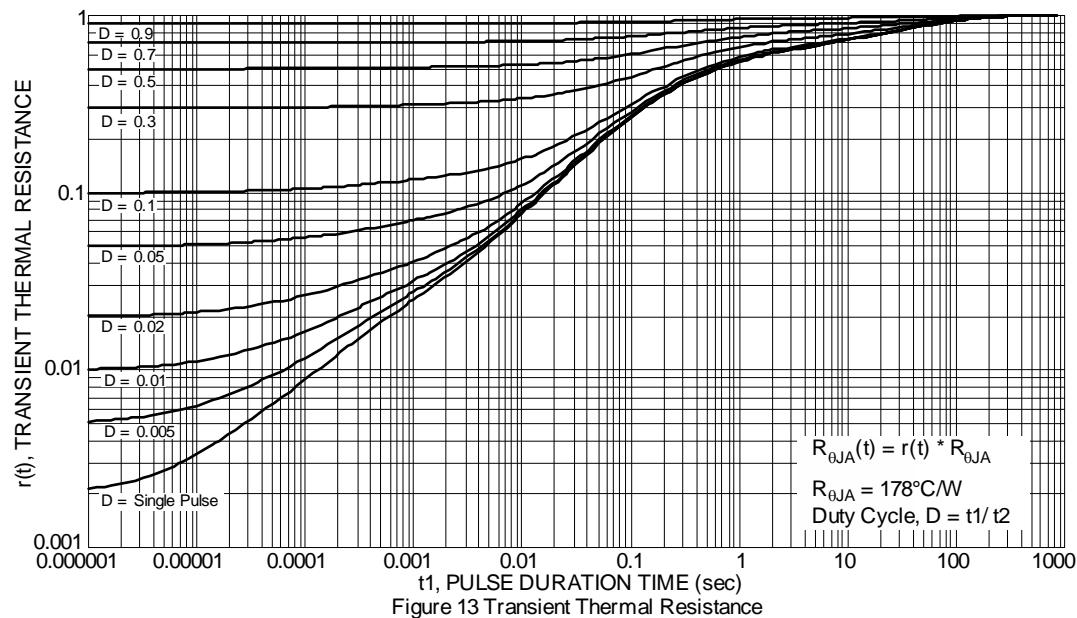
Figure 4 Typical Drain-Source On-Resistance  
vs. Gate-Source Voltage

Figure 6 On-Resistance Variation with Temperature

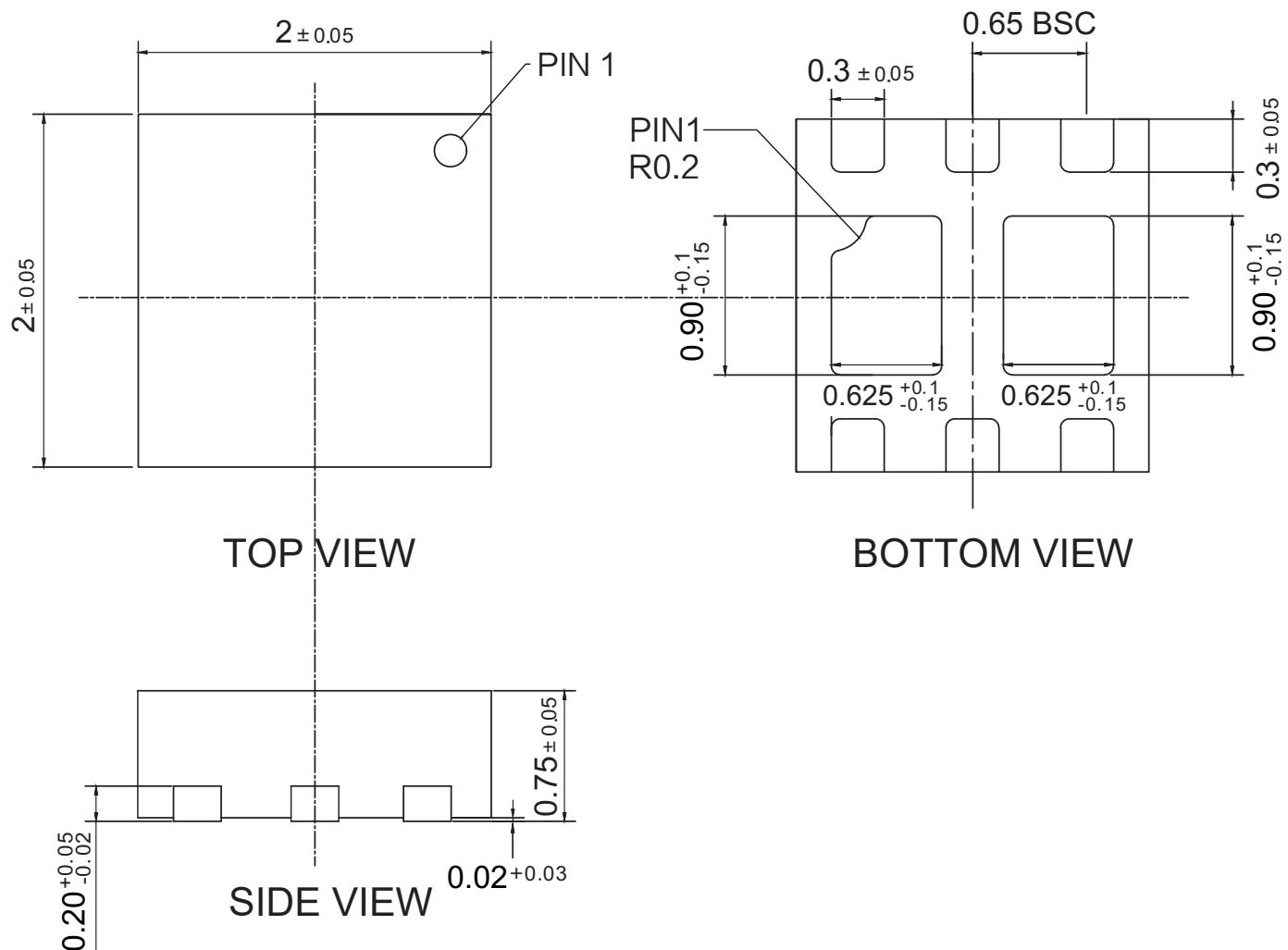




## Package Outline

DFN2x2-6L-0002

Dimensions in mm



## Ordering Information

Device	Package	Shipping
TN03DP20JDFA	DFN2x2A-6L	3,000PCS/Reel&7inches

## Contact Information

TANI website: <http://www.tanisemi.com> Email:tani@tanisemi.com

For additional information, please contact your local Sales Representative.



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